L Number	Hits	Search Text	DB	Time stamp
11	176		USPAT;	2004/03/24 09:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
12	176	333/33,34,247,260.ccls. and (MMW or MMIC)	USPAT;	2004/03/24 09:34
**	1,0	333,33,31,211,230.33131 and (i.i.i. 32 i.i.i.)	US-PGPUB;	2001,00,21 03.3
			EPO; JPO;	
			DERWENT;	
13	48	(SMA near connector\$1) and (thermal near	IBM_TDB USPAT;	2004/03/24 09:35
13	40	expansion)	US-PGPUB;	2004/03/24 09.3.
		Cirpano 2011,	EPO; JPO;	
			DERWENT;	
	100	057/4	IBM_TDB	0004/00/04 00 0
14	103	257/\$.ccls. and mmic and (thermal with coefficient)	USPAT; US-PGPUB;	2004/03/24 09:36
		Coefficient,	EPO; JPO;	
	:		DERWENT;	
	•		IBM_TDB	
16	19		USPAT;	2004/03/24 09:38
		microstrip and (thermal with coefficient)	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	22		USPAT;	2004/03/24 09:39
		(thermal with coefficient)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
18	218	333/33,34,247,246,260.ccls. and MMIC	USPAT;	2004/03/24 09:40
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
22	45	thermal and housing and MMW	USPAT;	2004/03/24 10:00
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
23	4	monolithic and (stress\$3 with relief with	USPAT;	2004/03/24 10:53
		portions) and (heat or thermal) and	US-PGPUB;	
		pedestal	EPO; JPO; DERWENT;	
			IBM TDB	
-	2620	333/33,34,247,260.ccls.	USPĀT;	2002/05/16 19:03
			US-PGPUB;	
]			EPO; JPO;	
			DERWENT; IBM TDB	
_	132	333/33,34,247,260.ccls. and (MMW or MMIC)	USPAT;	2004/03/24 09:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	10	((hous\$3 or enclos\$4) with transceiver\$1)	USPĀT;	2003/08/11 09:13
		and (MMW or MMIC)	US-PGPUB;	
			EPO; JPO;	
	:		DERWENT;	
_	0	333/33,34,247,260.ccls. and (MMW with	USPAT;	2002/05/16 19:00
		module\$1)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	0	333/33,34,247,260.ccls. and (MMW same	USPAT;	2002/05/16 19:00
		module\$1)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
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